



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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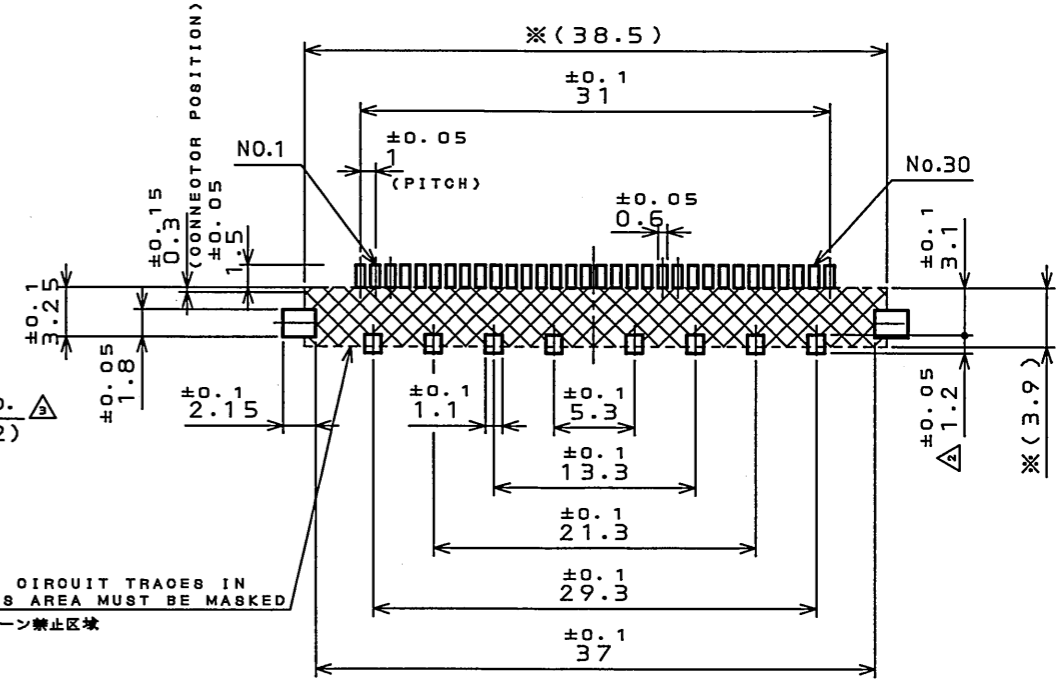
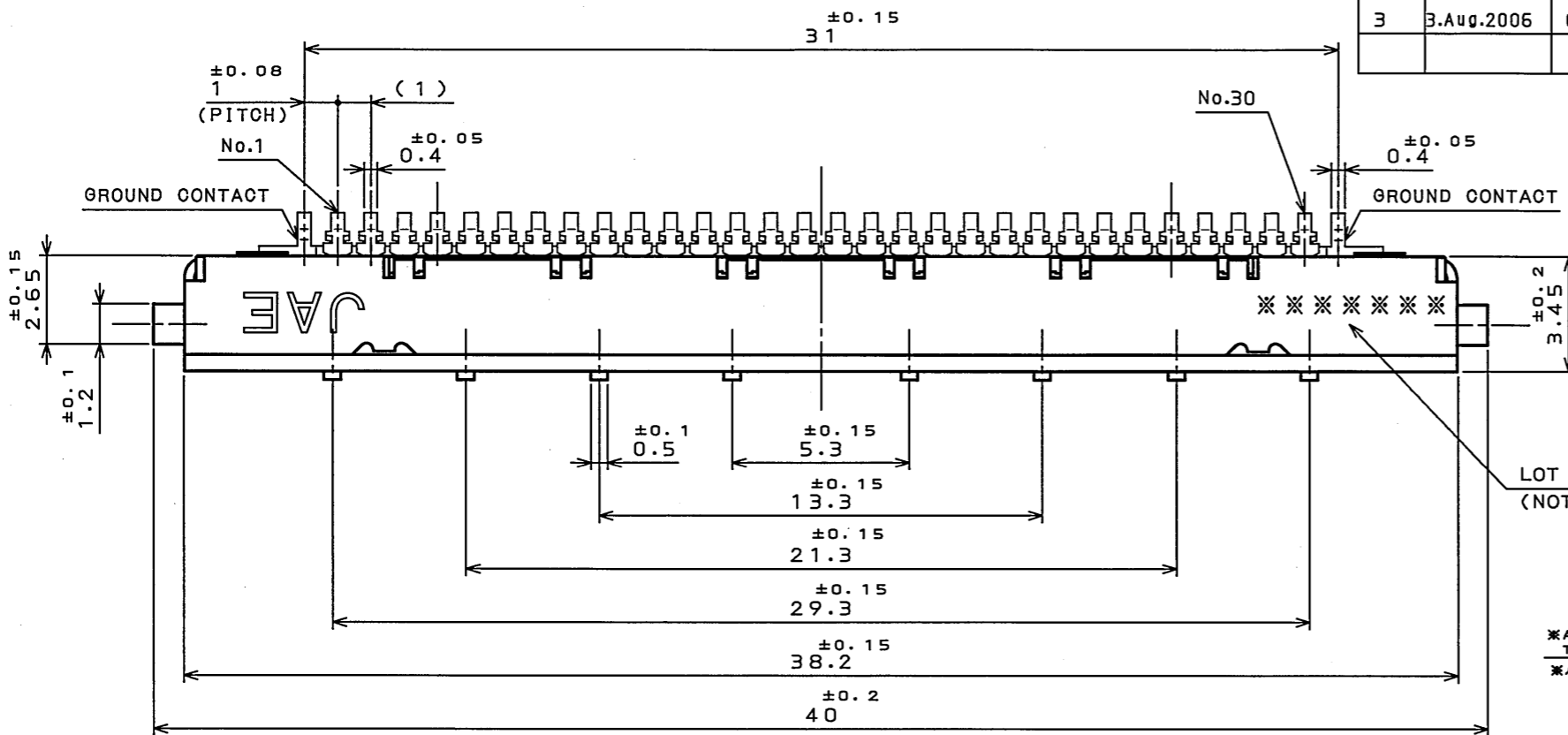
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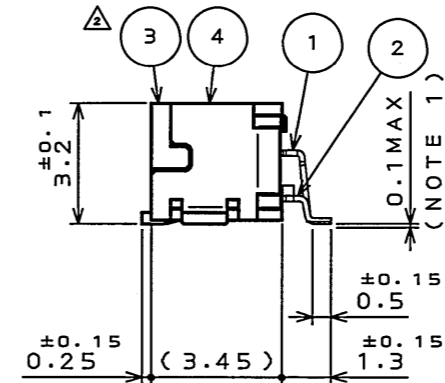
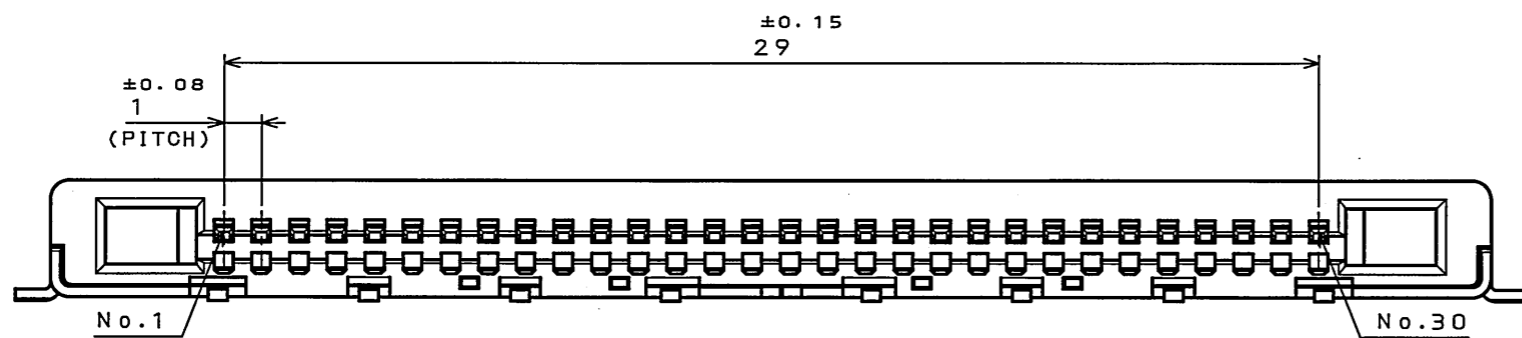
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(ON ENIMVH)各要図

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	18.Mar.2004	054650	ADDED DIMENSIN etc 寸法追加、他		K.HISAMATSU	M.SUZUKI	Y.ICHIIYAMA
3	3.Aug.2006	060641	ADDED LOT No. AND NOTE. ロットNo.と注記追加	M.ABE	K.HISAMATSU	M. Suzuki	K. Hisatome



△ LOT No. (NOTE2)
*ANY CIRCUIT TRACES IN THIS AREA MUST BE MASKED
*パターン禁止区域

APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法(参考)



符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	SHELL シェル	1	STAINLESS STEEL ステンレス	TIN PLATING スス・メッキ	
3	INSULATOR インシュレータ	1	HEAT RESISTING PLASTIC 耐熱性プラスチック		UL94 V-0
2	GROUND PLATE クラントプレート	1	COPPER ALLOY 銅合金	TIN PLATING スス・メッキ	
1	CONTACT コンタクト	30	COPPER ALLOY 銅合金	TABLE 1	

仕様書 (SPECIFICATION)		第1版 (ORIGINAL DATE)		尺度 (SCALE)	シリーズ (SERIES)	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. 図面番号 (DRAWING NO.) SJ038770	版数 (REV.) 3
JACS-1752-*		2.Sep.2003		5:1	FI-E		
公差 (GENERAL TOLERANCE)		製図 DR.		名称 (TITLE)			
寸法 (DIMENSION) 角度 (ANGLES)		担当 CHK. M.TAKAKU		FI-E30S			
. ±0.8 ° ±		査閲 APPD.		質量 (MASS)			
.X ±0.4 °X ±		承認 APPD. Y.ICHIIYAMA		質量 (MASS)			
.XX ±0.1 °XX ±				質量 (MASS)			
.XXX ± °XXX ±				質量 (MASS)			

TABLE 1

CONTACT AREA 接触部	SOLDERING AREA 端子部
GOLD OVER NICKEL Ni上Au	TIN-COPPER OVER NICKEL Ni上SnCu

NOTE1. COPLANARITY BETWEEN TERMINAL AND HOLD DOWN OF SHELL SHOULD BE 0.1mm MAX.
△ 2. PRODUCTION LOT NUMBER AS INDICATED.
注1. 端子及び、シェルのホルルドダウンの相互のバラツキは0.1以内とする。
△ 2. 図示の位置にロット番号を表示する。

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